



COMMUNIQUE DE PRESSE

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Qualcomm Connecting New Market Segments with Gobi 3G Technology

— Company Addresses New Opportunities Beyond PCs by Increasing Flexibility for Customers and Expanding Range of Gobi Solutions —

BARCELONA, Spain — February 15, 2010 — [Qualcomm Incorporated](#) (Nasdaq: QCOM), a leading developer and innovator of advanced wireless technologies, products and services, today announced that the Company is expanding its focus to target new markets with its Gobi™ connectivity technology. Building on the success of Gobi technology in PC markets, the Company is collaborating with a wide range of companies to serve the needs of market segments such as e-readers, gaming devices and M2M commercial applications, in addition to continuing to enable connected computing beyond Wi-Fi hotspots with embedded modules and USB modems. The roadmap for Gobi technology also now features support for technologies such as HSPA+ and LTE.

“As a leading innovator in the consumer electronics industry, our choice for 3G connectivity is Gobi technology,” said Ryosuke Akahane, deputy president of VAIO Business Group, Sony. “We are pleased to be working with Qualcomm to expand the market for connected consumer devices while reaping the benefits of having a consistent software platform across our wireless products.”

Qualcomm will be working with multiple module and software companies on an expanded portfolio of flexible Gobi solutions across multiple chipsets that feature a consistent platform for application development to spur greater innovation across all Gobi-connected devices. Device manufacturers will benefit from a common software API across all of their Gobi-enabled products, thereby simplifying their software requirements while addressing a wide range of module requirements. The common software API also translates to a larger addressable market for independent software vendors (ISVs), which can take advantage of the inherent connectivity of Gobi-equipped devices to bring new types of mobile applications to market.

Qualcomm’s Gobi technology is currently in more than 50 notebook and netbook models. Next-generation Gobi2000™ modules are being launched in more than 100 notebook and netbook designs. Gobi technology is also already found in e-readers, such as IREX’s DR 800SG, and in routers for M2M and enterprise applications. Gobi-enabled routers currently available include the Top Global MB7900, which was recently launched by Sprint, and the Digi WR44.

“Gobi has become synonymous with reliable, transparent and ubiquitous 3G connectivity for the laptop and netbook markets, and we are now expanding to include new market segments,” said Barry Matsumori, vice president of connectivity and wireless modules at Qualcomm CDMA Technologies. “We are very excited about working with our Gobi partners to bring connectivity to new types of devices, helping to make instant access to real-time information more integral and seamless than ever before.”

Qualcomm Incorporated (Nasdaq: QCOM) is a leader in developing and delivering innovative digital wireless communications products and services based on CDMA and other advanced technologies. Headquartered in San Diego, Calif., Qualcomm is included in the S&P 100 Index, the S&P 500 Index and is a 2009 FORTUNE 500 company. For more information, please visit Qualcomm around the Web:

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Except for the historical information contained herein, this news release contains forward-looking statements that are subject to risks and uncertainties, including the speed by which new market segments develop for Gobi™ connectivity technology, the Company’s ability to successfully work with multiple module and software companies on an expanded portfolio of flexible Gobi solutions across multiple chipsets, the Company’s ability to successfully design and have manufactured significant quantities of ASIC components on a timely and profitable basis, change in economic conditions of the various markets the Company serves, as well as the other risks detailed from time to time in the Company’s SEC reports, including the report on Form 10-K for the year ended September 27, 2009, and most recent Form 10-Q.

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